ABSTRACT OF THE DISCLOSURE

A semiconductor device has: a semiconductor substrate having an integrated circuit and an electrode that is connected electrically to the integrated circuit; a resin layer formed on a surface of the semiconductor substrate on which the electrode is formed, but avoiding the electrode; and a wiring layer that is connected electrically to the electrode and has a land which is located on the resin layer. A penetrating hole that exposes the resin layer is formed in the land.